

LISTING OF THE CLAIMS

This listing of claims, amended as indicated below, will replace all prior versions, and listings, of claims in the application

1. (Canceled)

2. (Currently Amended) An apparatus as claimed in claim [[1]] 21, wherein the predetermined distance is ~~determinable~~ determined by considering one or more factors in the group consisting of the thickness, size and elastic modulus of the die, the thickness and elastic modulus of the film, the interfacial adhesive strength between the die and the elastic surface of the film and the shape and size of the ejector pin.

3. (Currently Amended) An apparatus as claimed in claim [[1]] 21, wherein the predetermined distance is less than 1.2 mm from the edges of the die where the die is a silicon die of between 3 mm to 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.

4. (Currently Amended) An apparatus as claimed in claim [[1]] 21, wherein the predetermined distance is less than 1.6 mm from the edges of the die where the die is a silicon die of greater than 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.

5. (Currently Amended) An apparatus as claimed in claim [[1]] 21, wherein the predetermined distance is less than 0.5 mm from the edges of the die where the die is a gallium arsenide die of between 3 mm to 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.

6. (Currently Amended) An apparatus as claimed in claim 21, including a vacuum ejector platform for supporting a portion of the film on which the die to be detached is mounted while the film is contacted by the ejector device.

7. (Original) An apparatus as claimed in claim 6, including apertures corresponding substantially to positions of each corner of the die to be detached, wherein the ejector pins are houseable within the vacuum ejector platform and projectable through said apertures for contacting the die.

8. (Currently Amended) An apparatus as claimed in claim 21, wherein the ejector device comprises at least four ejector pins, each ejector pin corresponding to a position substantially at a corner of the die.

9. (Original) An apparatus as claimed in claim 8, including one or more ejector pins corresponding to a position substantially at a center portion of the die.

10. (Currently Amended) An apparatus as claimed in claim 21, wherein each ejector pin has an effective support area of at least $1 \times 10^{-4} \text{ mm}^2$.

11. (Withdrawn) A method of detaching a thin die mounted on an adhesive surface of a film, comprising the steps of:
contacting and raising a second surface of the film opposite the adhesive surface with a plurality of ejector pins at positions substantially at the corners of the die within a predetermined distance from the edges of said die;
pushing against the film using the plurality of ejector pins at the positions substantially at the corners of the die to partially delaminate the die; and
holding the partially-delaminated die and detaching the die from the adhesive surface.

12. (Withdrawn) A method as claimed in claim 11, including the step of determining the predetermined distance by considering one or more factors in the group consisting of the thickness, size and elastic modulus of the die, the thickness and elastic modulus of the film, the interfacial adhesive strength between the die and the elastic surface of the film and the shape and size of the ejector pin.

13. (Withdrawn) A method as claimed in claim 11, wherein the predetermined distance is less than 1.2 mm from the edges of the die where the die is a silicon die of between 3 mm to 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.

14. (Withdrawn) A method as claimed in claim 11, wherein the predetermined distance is less than 1.6 mm from the edges of the die where the die is a silicon die of greater than 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.

15. (Withdrawn) A method as claimed in claim 11, wherein the predetermined distance is less than 0.6 mm from the edges of the die where the die is a gallium arsenide die of between 3 mm to 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.

16. (Withdrawn) A method as claimed in claim 11, including generating a vacuum in a vacuum ejector platform to support a portion of the film on the second surface of the film which the die to be detached is mounted while contacting the film with the ejector pins.

17. (Withdrawn) A method as claimed in claim 16, further including raising the ejector pins from within the vacuum ejector platform through apertures formed thereon to the film at positions substantially at the corners of the die.

18. (Withdrawn) A method as claimed in claim 11, wherein there are at least four ejector pins, each ejector pin contacting the die substantially at a separate corner of the die.

19. (Withdrawn) A method as claimed in claim 18, including one or more ejector pins to separately contact substantially a center portion of the die.

20. (Withdrawn) A method as claimed in claim 11, wherein each ejector pin has an effective support area of at least $1 \times 10^{-4} \text{ mm}^2$.

21. (New) An apparatus for detachment of a thin die from a film, the film having a adhesive surface on which a plurality of dice are mounted, the apparatus comprising:
an ejector device comprising a plurality of ejector pins,
the ejector pins being operative to initiate detachment of a die from the film by contacting the film under the die on a second surface of the film opposite the adhesive surface substantially at the corners of the die within a predetermined distance from the edges of said die and by raising the film under the corners of the die to separate the film under the corners of die is separated from the die; and
a collet operative to detach the die from the film after detachment has been initiated by the ejector device, and to hold the die after detachment from the film.

22. (New) An apparatus as claimed in claim 9, wherein the ejector pins which contact the film substantially under the center portion of the die, do not make contact with the film before the ejector pins which contact the film substantially at the corners of the die.